



## SPECIFICATION

(Reference sheet)

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL10A106KP8NNNC
- Description : CAP, 10µF, 10V, ±10%, X5R, 0603

A. Samsung Part Number

		<u>CL</u> ①	<u>10</u> ②	<u>А</u> З	<u>106</u> ④	<u>K</u> 5	<u>Р</u> 6	<mark>8</mark> 7	<u>N</u> 8	<u>N</u> 9	<u>N</u> 10	<u>C</u> (1)	
-	Series Size	Samsung Mult 0603 (inch c	•	r Cer		•	citor ± 0.1		mm		W:	0.8 ± 0.1	mm
3 4 5	Dielectric Capacitance Capacitance tolerance	X5R 10 μF ±10 %				8	Inne Term Plati Prod	ninat ng		e	(	Ni Cu Sn 100% Normal	(Pb Free)
6) 7	Rated Voltage Thickness	10 V 0.8 ± 0.1	mm				Spec Pack		g			Reserved for Cardboard T	

## B. Samsung Reliability Test and Judgement condition

	Performance	Test condition					
Capacitance	Within specified tolerance	1kt±10% 0.5±0.1Vrms *A capacitor prior to measuring the capacitance is heat treated at 150 °C +0/-10 °C, and maintained in ambient air for 24±2 hours.					
Tan δ (DF)	0.1 max.						
Insulation	10,000Mohm or 100Mohm·μF	Rated Voltage 60~120 sec.					
Resistance	Whichever is Smaller						
Appearance	No abnormal exterior appearance	Microscope (×10)					
Withstanding	No dielectric breakdown or	250% of the rated voltage					
Voltage	mechanical breakdown						
Temperature	X5R						
Characteristics	(From -55 $^{\circ}$ to 85 $^{\circ}$ , Capacitance change should be within ±15%)						
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.					
of Termination	terminal electrode						
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm)					
		with 1.0mm/sec.					
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder					
	is to be soldered newly	245±5℃, 3±0.3sec.					
		(preheating : 80~120 ℃ for 10~30sec.)					
Resistance to	Capacitance change : within ±7.5%	Solder pot : 270±5℃, 10±1sec.					
Soldering heat	Tan δ, IR : initial spec.						

	Performance	Test condition				
Vibration Test	Capacitance change : within ±5%	Amplitude : 1.5mm				
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)				
		2hours $\times$ 3 direction (x, y, z)				
Moisture	Capacitance change : within ±12.5%	With rated voltage				
Resistance	Tan δ: 0.125 max	40±2℃, 90~95%RH, 500+12/-0hrs				
	IR : 500Mohm or 12.5Mohm $\cdot \mu F$					
	Whichever is Smaller					
High Temperature	Capacitance change : within ±12.5%	With 100% of the rated voltage				
Resistance	Tan δ: 0.125 max	Max. operating temperature				
	IR : 1,000Mohm or 25Mohm · μF					
	Whichever is Smaller	1000+48/-0hrs				
Temperature	Capacitance change : within ±7.5%	1 cycle condition				
Cycling	Tan δ, IR : initial spec.	Min. operating temperature $\rightarrow$ 25 °C				
		$\rightarrow$ Max. operating temperature $\rightarrow$ 25 °C				
		5 cycle test				

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5  $^\circ\!\!\!\mathrm{C}$  , 10sec. Max )

Product specifications included in the specifications are effective as of March 1, 2013. Please be advised that they are standard product specifications for reference only. We may change, modify or discontinue the product specifications without notice at any time. So, you need to approve the product specifications before placing an order. Should you have any question regarding the product specifications, please contact our sales personnel or application engineers.